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## KEYDATES

*Paper submission deadline:*

**18 April, 2016**

*Notification of acceptance:*

**6 June, 2016**

*Early registration deadline:*

**13 June, 2016**

## CONTACT

**Local Secretariat:** Isabelle Buzzi & Karin Jaymes, EPFL, Switzerland

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ESSDERC  
ESSCIRC

## GENERAL PURPOSE OF THE CONFERENCES

The aim of **ESSDERC** and **ESSCIRC** is to provide an annual European forum for the presentation and discussion of recent advances in solid-state devices and circuits. The increasing level of integration for system-on-chip design made available by advances in silicon technology is, more than ever before, calling for a deeper interaction among technologists, device experts, IC designers, and system designers. While keeping separate Technical Program Committees, **ESSCIRC** and **ESSDERC** are governed by a common Steering Committee and share Plenary Keynote Presentations and Joint Sessions bridging both communities. Attendees registered for either conference are encouraged to attend any of the scheduled parallel sessions, regardless to which conference they belong.

## CONFERENCE HIGHLIGHTS

- 3 joint keynote presentations
- 3 **ESSCIRC** keynote presentations
- 3 **ESSDERC** keynote presentations
- Invited papers with overall coverage of all aspects of advanced devices and circuits
- Special focus sessions covering device-circuit interactions in the field of Internet of Everything, wearables and emerging technologies
- One Joint Panel Discussion
- Presentation of IEEE and **ESSDERC/ESSCIRC** Awards
- **ESSDERC/ESSCIRC** Gala Diner presentation on Wednesday, September 14, 2016.
- For the first time, the conference organizes a single Tutorial and Workshop Day on Monday, September 12, 2016.

The venue for all conference events, including workshops and tutorials, is the SwissTech Convention Center on EPFL Campus. The working language of the conference is English.

## TOPICS FOR INCREASED PARTICIPATION

For the 2016 **ESSDERC/ESSCIRC** conference, increased participation is sought in the following areas:

- Sensors and circuits for Internet of Everything
- Wearable low power devices, circuits and systems with particular focus of flexible electronics
- Beyond CMOS devices, particularly the role of 2D materials, and their benchmarking at device and circuit level
- Power devices, circuits and applications
- Energy harvesting, storage and management
- Neuromorphic and quantum computing



**Lausanne** is in the heart of Europe, just 40 minutes from Geneva

International Airport; situated by Lake Geneva and renowned for its pleasant way of life,

this city seduces both business travelers and tourists alike. The capital of the canton of Vaud is part of the second fastest-growing economic region in the country. It is home to a large number of multinationals, more than 50, international sport federations and a multitude of start-ups, vocational schools and prestigious research centers. State-of-the-art infrastructure in keeping with the city's long-term commitment to sustainable development. Lausanne lends itself to trips by public transport, on foot or by bicycle. The surrounding area is similarly conducive to walks in the forest and in vineyards listed as UNESCO World Heritage sites. Don't miss the opportunity to join the conference and spend some unforgettable moments discovering our region!

<http://www.lausanne-tourisme.ch/fr/>

**EPFL** is Europe's most cosmopolitan institute of technology with students, staff and professors from over 120 nations.

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to Switzerland and the world, **EPFL** is centered on its three missions: teaching, research and technology transfer. **EPFL** works together with an extensive network of partners including other universities and institutes of technology, developing and emerging countries, secondary schools and colleges, industry and economy, political circles and the general public, to bring about real impact for society.

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